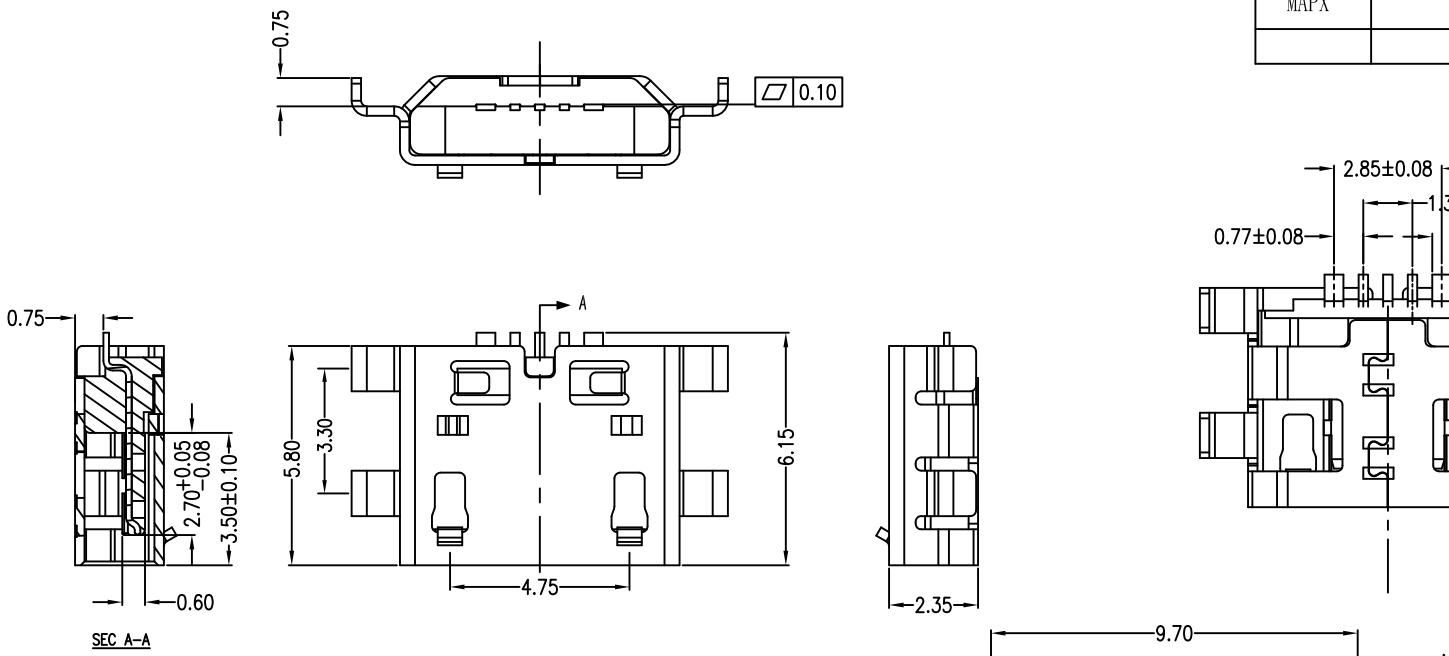
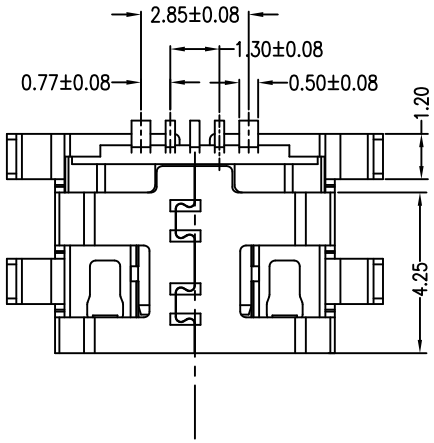
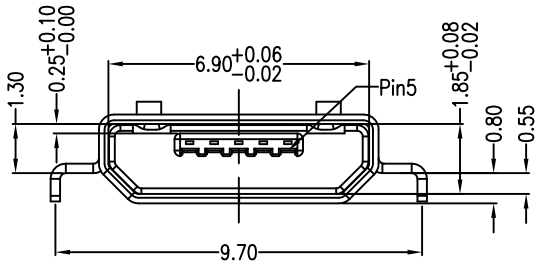
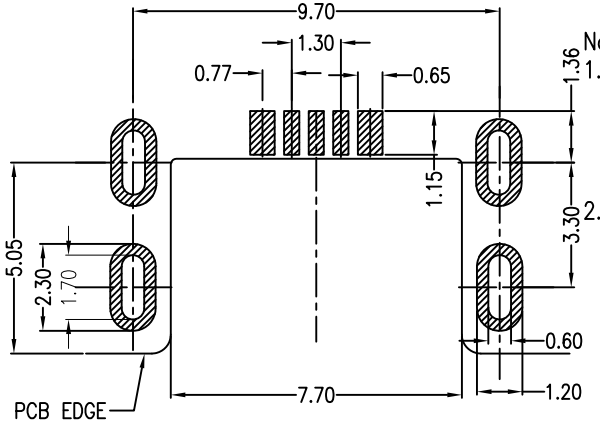
MAPX	MODIFICATION	DATE









RECOMMANDED PCB LAYOUT

PCB图仅供参考

Note:

1.Material:

1.1 Housing: High temperature thermoplastic with g.f,UL94v-0

1.2 Contact: copper alloy,t=0.15mm

1.3 Shell: SUS,t=0.25mm

2.Specification:

2.1 Current rating:1,5PIN 3A Max/2,3,4PIN 1A Max.

2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.

2.3 Contact resistance: 30 mΩ Max.

2.4 Insulation resistance: 100 MΩ Min.

2.5 Total mating force: 3.57 Kgf Max.

2.6 Total unmating force: 1.0 Kgf Min.

2.7 Temperature range: -30°C~80°C

A 01 S B X X X X X XX-670

① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

⑤ 外壳材质 1:C2680R-H 7:SUS304R-1/2H

⑥ 外壳电镀 1:N50u'' 2:雾T50u'' 3:N+Au1u''(脚) 4:Au1u''

⑦ 端子材质 4:C5191R-EH

⑧ 主体材质 1:LCP

⑨ 主体颜色 B:黑色

⑩ 端子电镀 01:Au1u'';02:Au1.5u'';03:Au3u'' 05:Au5u'' ;10:Au10u'';15:Au15u'';30:Au30u''

产品图 PRODUCT CHART DWG				深圳市精拓金电子有限公司							
公差一览表 TOLERANCE UNLESS OTHERWISE				单位 UNITS	MM	制图 DRAWING	邱建辉	制图料号 PRODUCT PART NO.			
X.	±0.15	X.	±5.°	比例 SCALE	1:1	审核 CHKD	郭治富	产品名称 PRODUCT NO.	Micro usb 5s B Type沉板0.8四脚全插无导位无孔双卡点1.5Pin加宽		
.X	±0.10	.X	±2.°								
.XX	±0.05	.XX	±1.°	日期 DATE	2013.12.23	核准 APPD	黄国荣	角法 VIEW		版本 VER	A0
.XXX	±0.03	.XXX	±0.5°								